

Technical Data Sheet

Thermal Floor Panel MP741 & MP744 is a composite insulation and chipboard flooring panel designed for use on concrete floor bases.

PRODUCT

Thermal Floor Panel MP741 & MP744 is suitable for new and refurbished buildings, conservatories and extensions using a variety of insulants.

Consisting of a moisture resistant chipboard factory-bonded to a thermal insulation layer to improve thermal performance through the floor structure.

SPECIFICATION

- Easy to cut and install
- One operation saves time
- Ready for floor covering
- Excellent thermal insulation

Extruded Polystyrene Thickness: 25mm, 35mm, 50mm

Expanded Polystyrene Thickness: 20mm, 25mm, 50mm

PIR Thickness: 20mm, 25mm, 50mm

Chipboard Thickness: 18mm or 22mm

Panel Size: 2400 x 600mm

Other insulant thicknesses are available



Thermal floor panel with T&G edges highlighted.

PRODUCT PERFORMANCE

	COMPRESSIVE STRENGTH	THERMAL CONDUCTIVITY
Extruded Polystyrene	200 kPa	0.033 W/mK
Expanded Polystyrene	70 kPa	0.038 W/mK
PIR	140 kPa	0.023 W/mK

Chipboard

C4 V313 Moisture Resistant Grade

Thermal Conductivity: 0.14 W/mK